



ALPHA & OMEGA
SEMICONDUCTOR

AO4488
30V N-Channel MOSFET

General Description

The AO4488 uses advanced trench technology to provide excellent $R_{DS(ON)}$ with low gate charge. This device is ESD protected and it is suitable for use as a load switch or in PWM applications.

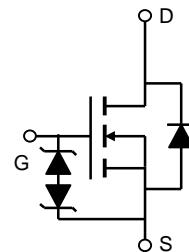
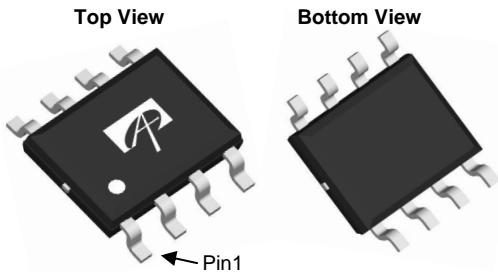
Product Summary

V_{DS} (V) = 30V
 I_D = 20A (V_{GS} = 10V)
 $R_{DS(ON)} < 4.6\text{m}\Omega$ (V_{GS} = 10V)
 $R_{DS(ON)} < 6.4\text{m}\Omega$ (V_{GS} = 4.5V)

ESD Protected
100% UIS Tested
100% R_g Tested



SOIC-8



Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	10 Sec	Steady State	Units
Drain-Source Voltage	V_{DS}	30		V
Gate-Source Voltage	V_{GS}	± 20		V
Continuous Drain Current ^A $T_A=25^\circ\text{C}$	I_D	20	15	A
$T_A=70^\circ\text{C}$	I_D	17	12	
Pulsed Drain Current ^B	I_{DM}	80		
Avalanche Current ^G	I_{AR}	50		
Repetitive avalanche energy $L=0.3\text{mH}$ ^G	E_{AR}	375		mJ
Power Dissipation ^A $T_A=25^\circ\text{C}$	P_D	3.1	1.7	W
$T_A=70^\circ\text{C}$	P_D	2.0	1.1	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150		°C

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A $t \leq 10\text{s}$	$R_{\theta JA}$	31	40	°C/W
Maximum Junction-to-Ambient ^A Steady State		59	75	°C/W
Maximum Junction-to-Lead ^C Steady State	$R_{\theta JL}$	16	24	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$	30	35.5		V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 30\text{V}, V_{GS} = 0\text{V}$		1		μA
		$T_J = 55^\circ\text{C}$		5		
I_{GSS}	Gate-Body leakage current	$V_{DS} = 0\text{V}, V_{GS} = \pm 16\text{V}$			± 10	
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	1.0	1.7	2.5	V
$I_{\text{D(ON)}}$	On state drain current	$V_{GS} = 10\text{V}, V_{DS} = 5\text{V}$	80			A
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{GS} = 10\text{V}, I_D = 20\text{A}$		3.8	4.6	$\text{m}\Omega$
		$T_J = 125^\circ\text{C}$		5.3	6.5	
		$V_{GS} = 4.5\text{V}, I_D = 18\text{A}$		5.2	6.4	
g_{FS}	Forward Transconductance	$V_{DS} = 5\text{V}, I_D = 20\text{A}$		72		S
V_{SD}	Diode Forward Voltage	$I_S = 1\text{A}, V_{GS} = 0\text{V}$		0.69	1	V
I_S	Maximum Body-Diode Continuous Current				3	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=15\text{V}, f=1\text{MHz}$		5450	6800	pF
C_{oss}	Output Capacitance			760		pF
C_{rss}	Reverse Transfer Capacitance			540		pF
R_g	Gate resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$		1	1.5	Ω
SWITCHING PARAMETERS						
$Q_g(10\text{V})$	Total Gate Charge	$V_{GS}=10\text{V}, V_{DS}=15\text{V}, I_D=20\text{A}$		84	112	nC
$Q_g(4.5\text{V})$	Total Gate Charge			42	56	nC
Q_{gs}	Gate Source Charge			12		nC
Q_{gd}	Gate Drain Charge			21		nC
$t_{\text{D(on)}}$	Turn-On DelayTime	$V_{GS}=10\text{V}, V_{DS}=15\text{V}, R_L=0.75\Omega, R_{\text{GEN}}=3\Omega$		13		ns
t_r	Turn-On Rise Time			9.8		ns
$t_{\text{D(off)}}$	Turn-Off DelayTime			49		ns
t_f	Turn-Off Fall Time			16		ns
t_{rr}	Body Diode Reverse Recovery Time	$I_F=20\text{A}, dI/dt=100\text{A}/\mu\text{s}$		42	56	ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F=20\text{A}, dI/dt=100\text{A}/\mu\text{s}$		31		nC

A: The value of $R_{\theta JA}$ is measured with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$. The value in any given application depends on the user's specific board design. The current rating is based on the $t \leq 10\text{s}$ thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C. The $R_{\theta JA}$ is the sum of the thermal impedance from junction to lead $R_{\theta JL}$ and lead to ambient.

D. The static characteristics in Figures 1 to 6 are obtained using < 300 μs pulses, duty cycle 0.5% max.

E. These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The SOA curve provides a single pulse rating.

F. The current rating is based on the $t \leq 10\text{s}$ thermal resistance rating.

G. E_{AR} and I_{AR} ratings are based on low frequency and duty cycles to keep $T_J=25^\circ\text{C}$.

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

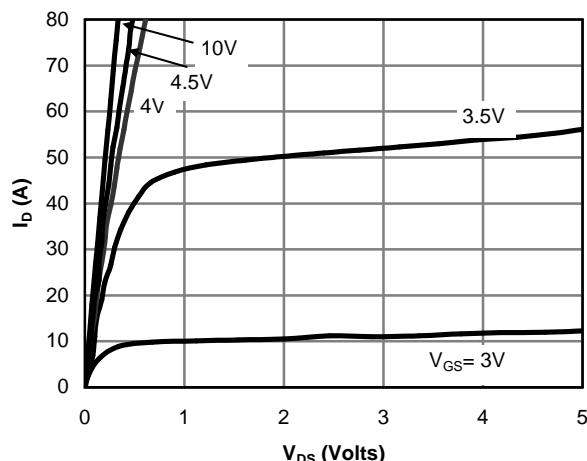


Figure 1: On-Region Characteristics

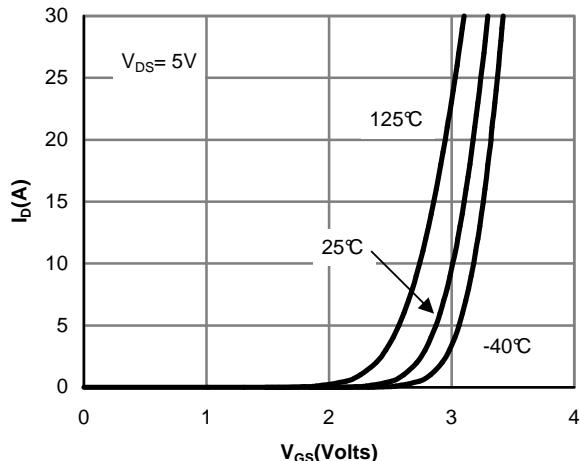


Figure 2: Transfer Characteristics

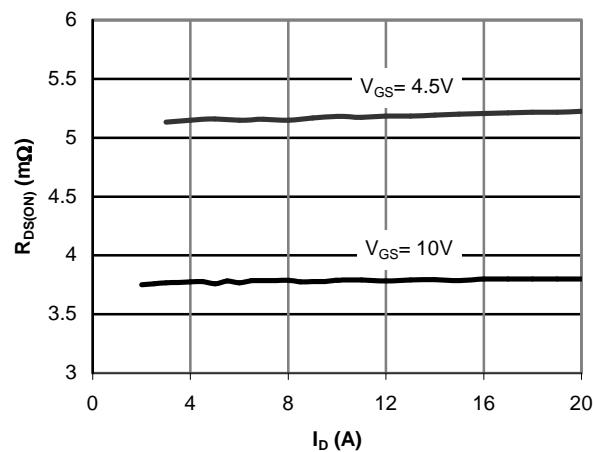


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

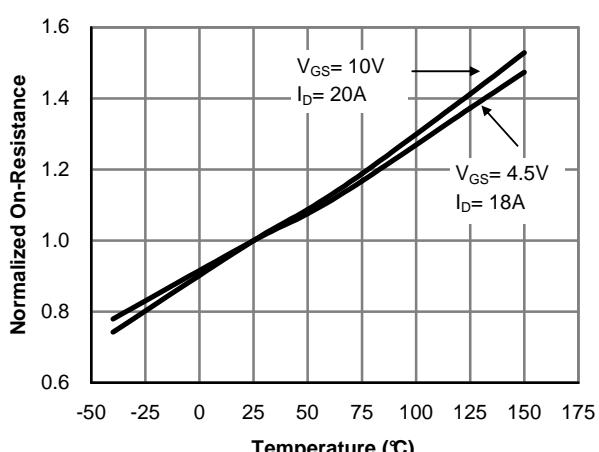


Figure 4: On-Resistance vs. Junction Temperature

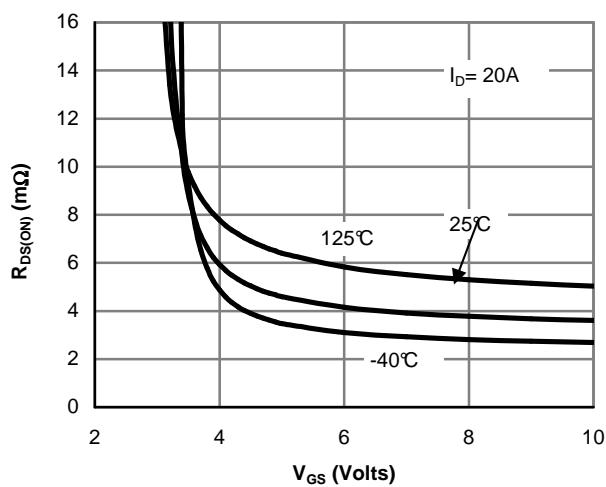


Figure 5: On-Resistance vs. Gate-Source Voltage

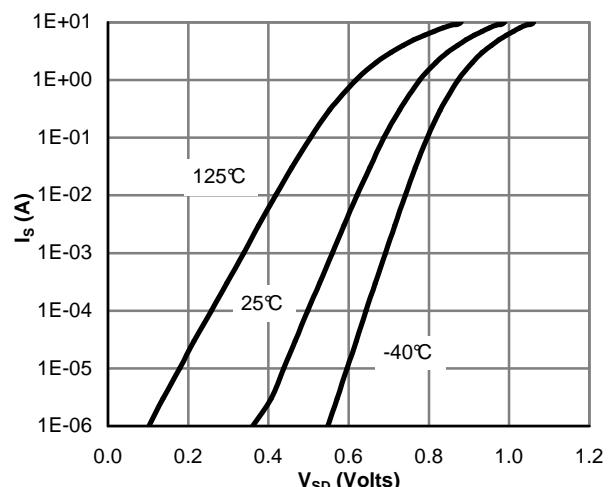


Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

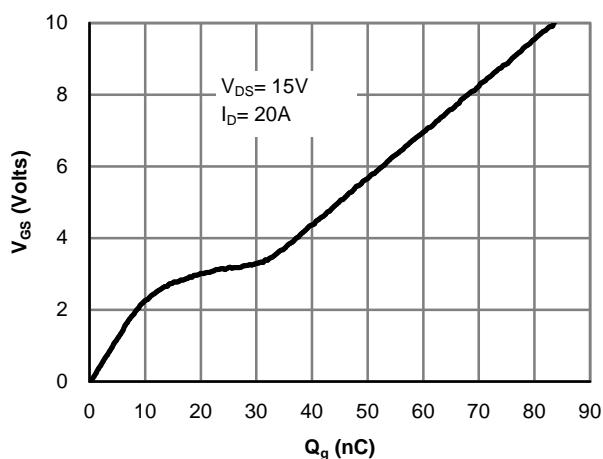


Figure 7: Gate-Charge Characteristics

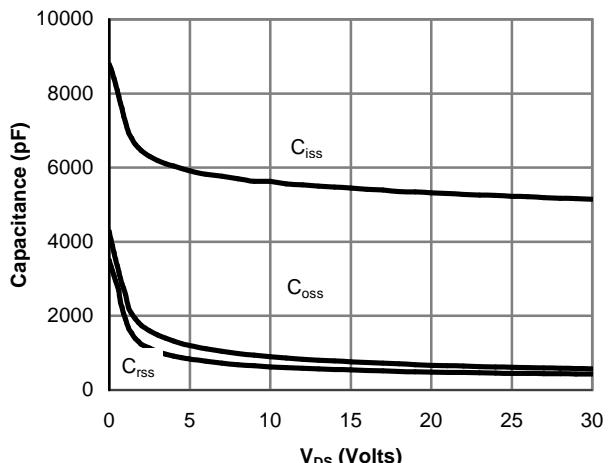


Figure 8: Capacitance Characteristics

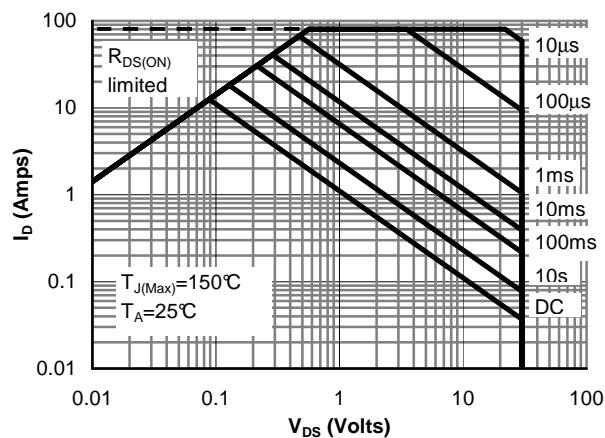


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

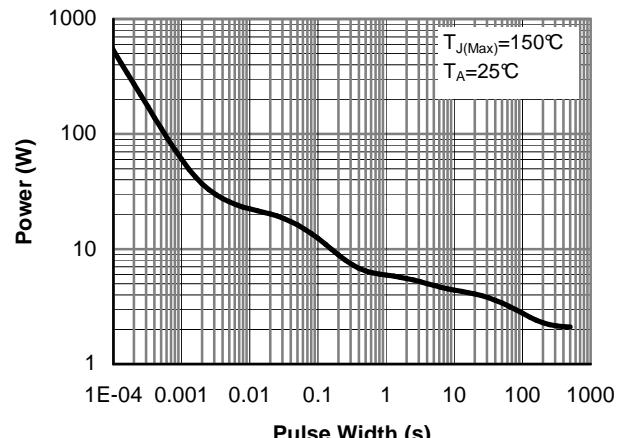


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

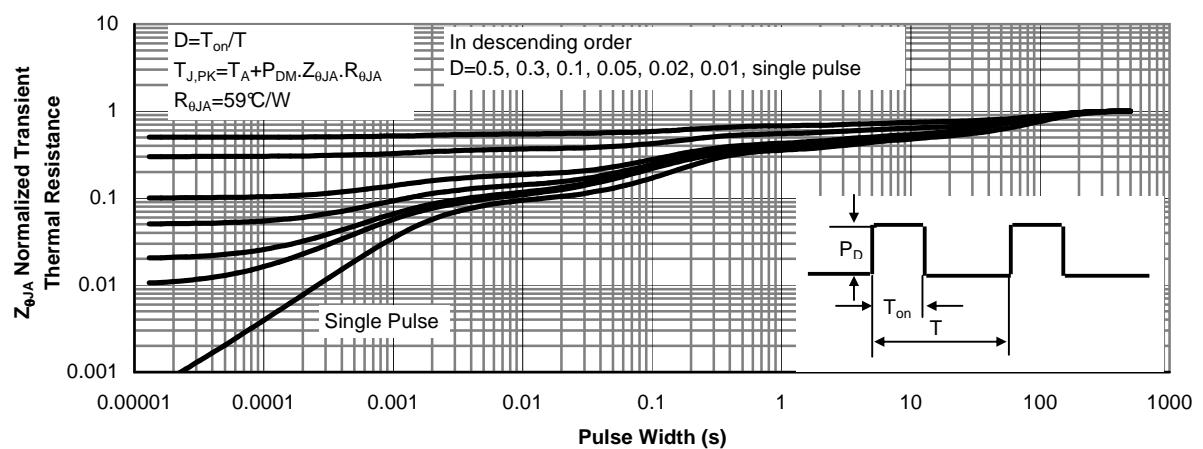
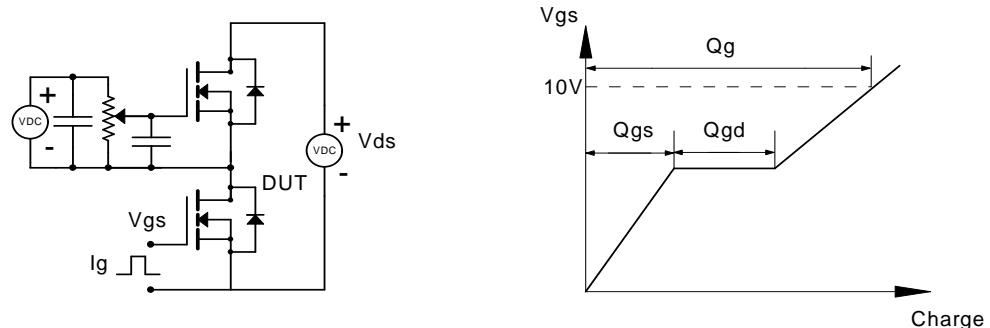
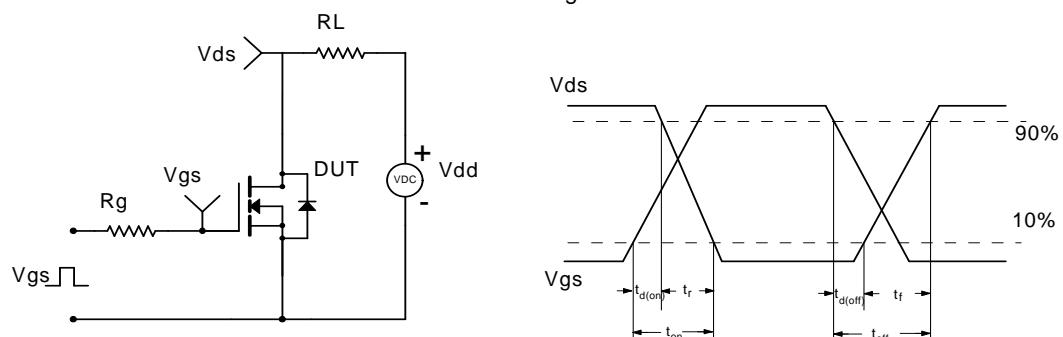


Figure 11: Normalized Maximum Transient Thermal Impedance (Note E)

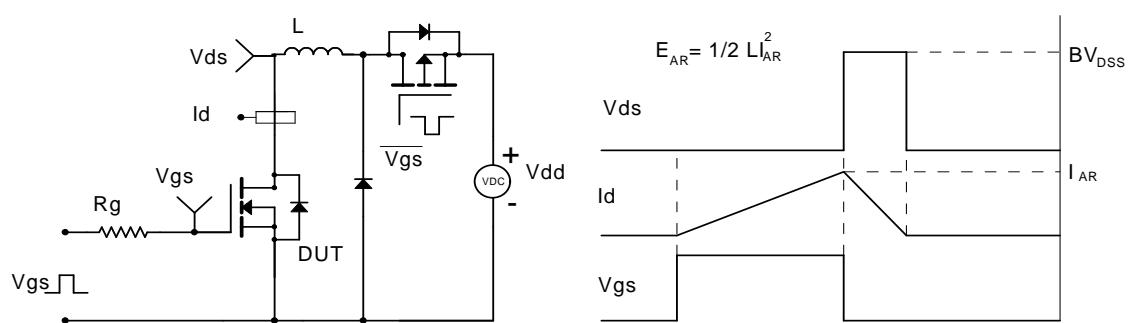
Gate Charge Test Circuit & Waveform



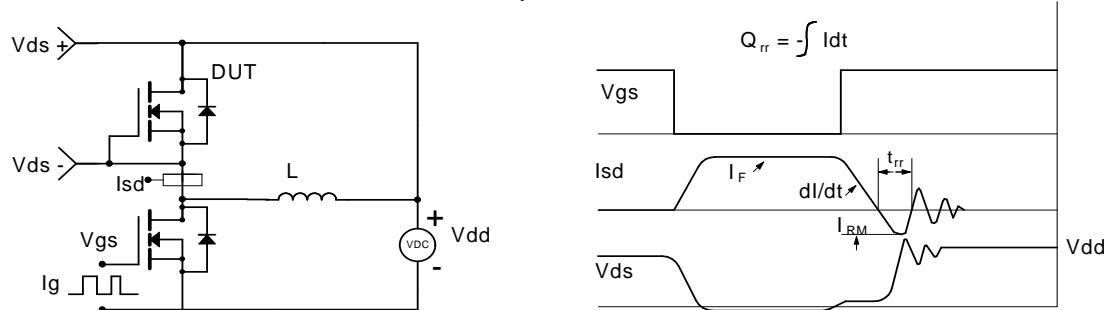
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



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